Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



**Top Material: Al**

**Backside Material: CrNiAg**

**Bond Pad Size: G= .021” X” .025”**

**Backside Potential: DRAIN**

**Mask Ref: HEX 4 - GEN V**

**APPROVED BY: DK DIE SIZE .170” X .230” DATE: 3/8/23**

**MFG: INT’L RECTIFIER THICKNESS .015” P/N: IRFC5210**

**DG 10.1.2**

#### Rev B, 7/19/02